COMPONENTS MARKED 'DNIP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01598</th>
<th>REV: E1</th>
<th>SVN REV: Not In VersionControl</th>
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<td></td>
<td>TID #: 01598</td>
<td></td>
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<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 5/1/2018 10:27:31 AM</td>
<td>TEXAS INSTRUMENTS</td>
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